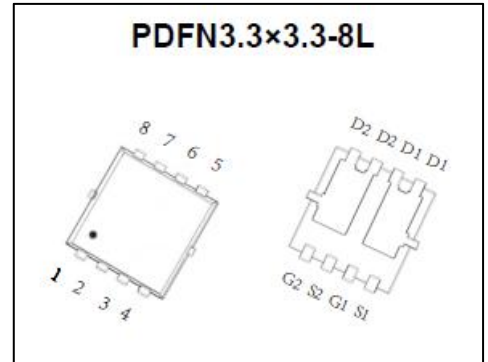




**PDFN3.3\*3.3-8L Plastic-Encapsulate MOSFETS**

**CCM2G04D06T N+P Channel Power MOSFET**

	N-CHANNEL	P-CHANNEL
V <sub>DS</sub> (V)	60	-60
R <sub>DS(on)</sub> (mΩ) at V <sub>GS</sub> = ± 10 V	30	62
R <sub>DS(on)</sub> (mΩ) at V <sub>GS</sub> = ± 4.5 V	37	75
I <sub>D</sub> (A)	5	-3.8



**DESCRIPTION**

The CCM2G04D06T provides excellent R<sub>DS(ON)</sub> with low gate charge. It can be used in a wide variety of applications .

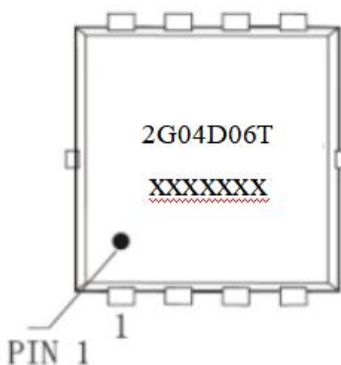
**FEATURES**

- Surface Mount Package
- Super High Density Cell Design for Extremely Low RDS(on)
- AEC Q101 qualified

**APPLICATIONS**

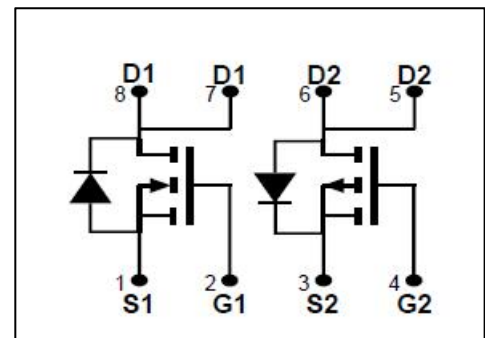
- CCFL Inverter
- Motor driven

**MARKING**



2G04D06T =Part No.  
XXXXXXX = Code.

**EQUIVALENT CIRCUIT**



**ABSOLUTE MAXIMUM RATINGS( $T_c=25^{\circ}\text{C}$  unless otherwise noted)**

Parameter	Symbol	N-CHANNEL	P-CHANNEL	Unit
Drain-Source Voltage	$V_{DS}$	60	-60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$		
Continuous Drain Current <sup>13</sup>	$I_D$	5	-3.8	A
Pulsed Drain Current <sup>4</sup>	$I_{DM}$	20	-16	
Single Pulse Avalanche Energy <sup>2</sup>	$E_{AS}$	2.25		mJ
Maximum Power Dissipation <sup>3</sup>	$P_D$	27		W
Thermal Resistance from Junction to Ambient <sup>3</sup>	$R_{\theta Ja}$	80		$^{\circ}\text{C/W}$
Thermal Resistance from Junction to Case	$R_{\theta Jc}$	5.5		$^{\circ}\text{C/W}$
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55~ +175		$^{\circ}\text{C}$
Lead Temperature for Soldering Purposes(1/8" from case for 10 s)	$T_L$	260		$^{\circ}\text{C}$

**Notes:**

1. The maximum current rating is limited by package.
2. EAS condition:  $V_{DD}=20\text{V}, V_{GS}=10\text{V}, I_{as}=3\text{A}, L=0.5\text{mH}, R_g=25\Omega$  Starting  $T_J = 25^{\circ}\text{C}$ .
3. Device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^{\circ}\text{C}$ .
4. Pulse Test : Pulse Width  $\leq 10\mu\text{s}$ , duty cycle  $\leq 1\%$ .

# MOSFET ELECTRICAL CHARACTERISTICS(TC=25°C unless otherwise specified)

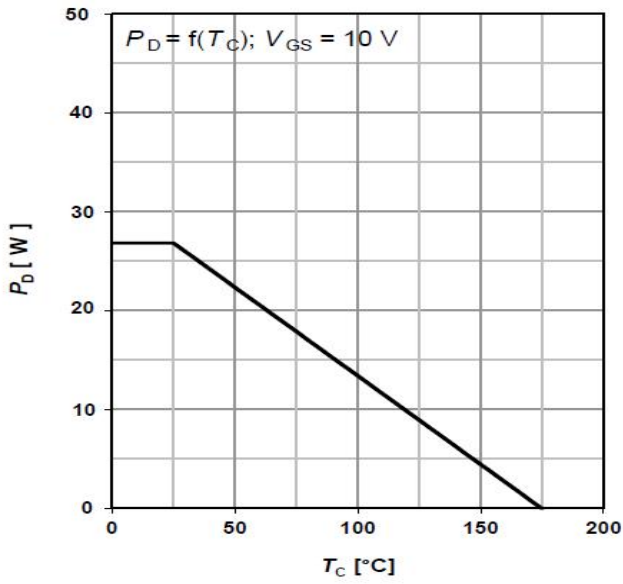
Parameter	Symbol	Test Condition		Min	Typ	Max	Unit
<b>Off characteristics</b>							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$		N-Ch	60		V
		$V_{GS} = 0\text{ V}, I_D = -250\ \mu\text{A}$		P-Ch	-60		
Gate-Source Leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$		N-Ch	-	$\pm 100$	nA
				P-Ch	-	$\pm 100$	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 60\text{ V}$	N-Ch	-	-	1
		$V_{GS} = 0\text{ V}$	$V_{DS} = -60\text{ V}$	P-Ch	-	-	-1
<b>On characteristics<sup>1</sup></b>							
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$		N-Ch	1.0	1.6	3.0
		$V_{DS} = V_{GS}, I_D = -250\ \mu\text{A}$		P-Ch	-1.0	-2.0	-3.0
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$	$I_D = 5\text{ A}$	N-Ch	-	30	40
		$V_{GS} = -10\text{ V}$	$I_D = -3.8\text{ A}$	P-Ch	-	62	80
		$V_{GS} = 4.5\text{ V}$	$I_D = 3.9\text{ A}$	N-Ch	-	37	55
		$V_{GS} = -4.5\text{ V}$	$I_D = -2\text{ A}$	P-Ch	-	75	110
Forward Transconductance	$g_{fs}$	$V_{DS} = 15\text{ V}, I_D = 4.3\text{ A}$		N-Ch	-	15	-
		$V_{DS} = -15\text{ V}, I_D = -3.1\text{ A}$		P-Ch	-	8.5	-
<b>Dynamic characteristics</b>							
Input Capacitance	$C_{iss}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 15\text{ V}, f = 1\text{ MHz}$	N-Ch	-	665	865
		$V_{GS} = 0\text{ V}$	$V_{DS} = -15\text{ V}, f = 1\text{ MHz}$	P-Ch	-	650	845
Output Capacitance	$C_{oss}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 15\text{ V}, f = 1\text{ MHz}$	N-Ch	-	75	97
		$V_{GS} = 0\text{ V}$	$V_{DS} = -15\text{ V}, f = 1\text{ MHz}$	P-Ch	-	95	124
Reverse Transfer Capacitance	$C_{rss}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 15\text{ V}, f = 1\text{ MHz}$	N-Ch	-	40	52
		$V_{GS} = 0\text{ V}$	$V_{DS} = -15\text{ V}, f = 1\text{ MHz}$	P-Ch	-	60	78
Gate Resistance	$R_g$	$f = 1\text{ MHz}$		N-Ch		3	
				P-Ch		20	
<b>Switching characteristics</b>							
Total Gate Charge	$Q_g$	$V_{GS} = 4.5\text{ V}$	$V_{DD} = 30\text{ V}, I_D = 4.3\text{ A}$	N-Ch	-		9
		$V_{GS} = -4.5\text{ V}$	$V_{DD} = -30\text{ V}, I_D = -3.1\text{ A}$	P-Ch	-		12
Gate-Source Charge	$Q_{gs}$	$V_{GS} = 4.5\text{ V}$	$V_{DD} = 30\text{ V}, I_D = 4.3\text{ A}$	N-Ch	-	2.3	-
		$V_{GS} = -4.5\text{ V}$	$V_{DD} = -30\text{ V}, I_D = -3.1\text{ A}$	P-Ch	-	2.2	-
Gate-Drain Charge	$Q_{gd}$	$V_{GS} = 4.5\text{ V}$	$V_{DD} = 30\text{ V}, I_D = 4.3\text{ A}$	N-Ch	-	2.6	-
		$V_{GS} = -4.5\text{ V}$	$V_{DD} = -30\text{ V}, I_D = -3.1\text{ A}$	P-Ch	-	3.7	-
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 30\text{ V}, I_D = 3.4\text{ A}, V_{GS} = 4.5\text{ V}, R_g = 1\ \Omega$		N-Ch	-	25	
		$V_{DD} = -30\text{ V}, I_D = -2.4\text{ A}, V_{GS} = -4.5\text{ V}, R_g = 1\ \Omega$		P-Ch	-	45	
Rise Time	$t_r$	$V_{DD} = 30\text{ V}, I_D = 3.4\text{ A}, V_{GS} = 4.5\text{ V}, R_g = 1\ \Omega$		N-Ch	-	100	
		$V_{DD} = -30\text{ V}, I_D = -2.4\text{ A}, V_{GS} = -4.5\text{ V}, R_g = 1\ \Omega$		P-Ch	-	105	
Turn-Off Delay Time	$t_{d(off)}$	$V_{DD} = 30\text{ V}, I_D = 3.4\text{ A}, V_{GS} = 4.5\text{ V}, R_g = 1\ \Omega$		N-Ch	-	25	
		$V_{DD} = -30\text{ V}, I_D = -2.4\text{ A}, V_{GS} = -4.5\text{ V}, R_g = 1\ \Omega$		P-Ch	-	60	
Fall Time	$t_f$	$V_{DD} = 30\text{ V}, I_D = 3.4\text{ A}, V_{GS} = 4.5\text{ V}, R_g = 1\ \Omega$		N-Ch	-	15	
		$V_{DD} = -30\text{ V}, I_D = -2.4\text{ A}, V_{GS} = -4.5\text{ V}, R_g = 1\ \Omega$		P-Ch	-	45	
<b>Drain-Source Diode Characteristics</b>							
Forward Voltage <sup>1</sup>	$V_{SD}$	$I_S = 1.7\text{ A}$		N-Ch	-		1.2
		$I_S = -2\text{ A}$		P-Ch	-		-1.2
Continuous drain-source diode forward Current	$I_S$			N-Ch			5
				P-Ch			-3.8
Pulsed Current	$I_{SM}$			N-Ch	-	-	20
				P-Ch	-	-	-16
Reverse recovery time	$T_{rr}$	$I_F = 4.5\text{ A}, dI/dt = 100\text{ A/us}$		N-Ch		10	
		$I_F = -3.5\text{ A}, dI/dt = 100\text{ A/us}$		P-Ch		18	
Reverse recovery charge	$Q_{rr}$	$I_F = 4.5\text{ A}, dI/dt = 100\text{ A/us}$		N-Ch		14	
		$I_F = -3.5\text{ A}, dI/dt = 100\text{ A/us}$		P-Ch		12	

## Notes:

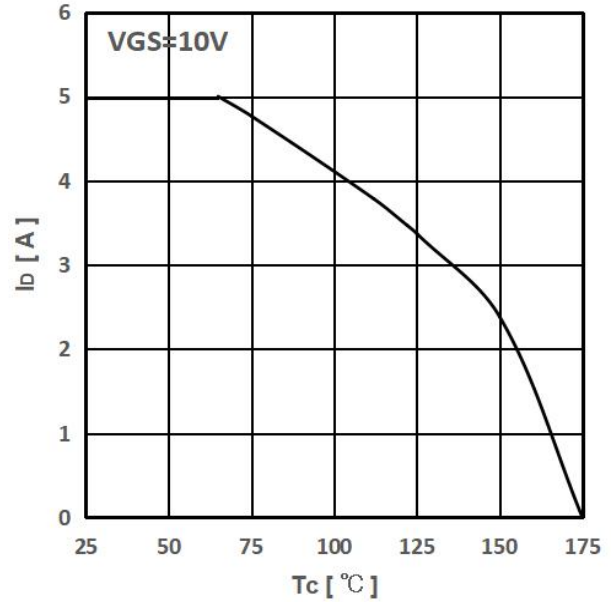
1. Pulse test; pulse width = 300  $\mu\text{s}$ , duty cycle  $\leq 2\%$ .

# N-Channel Typical Characteristics

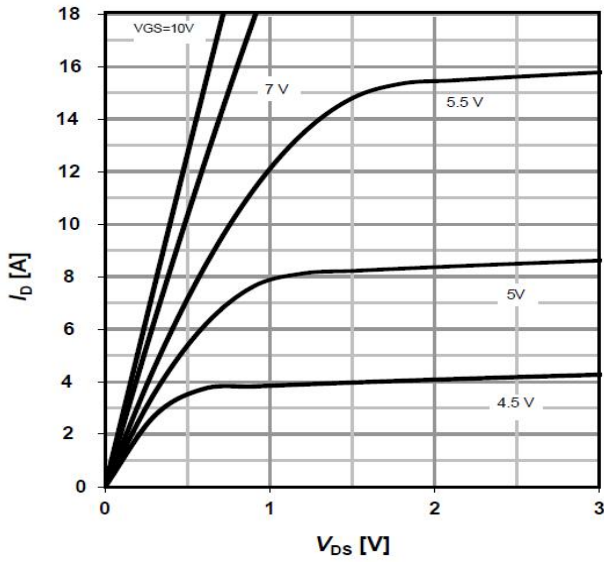
PD -- Tc



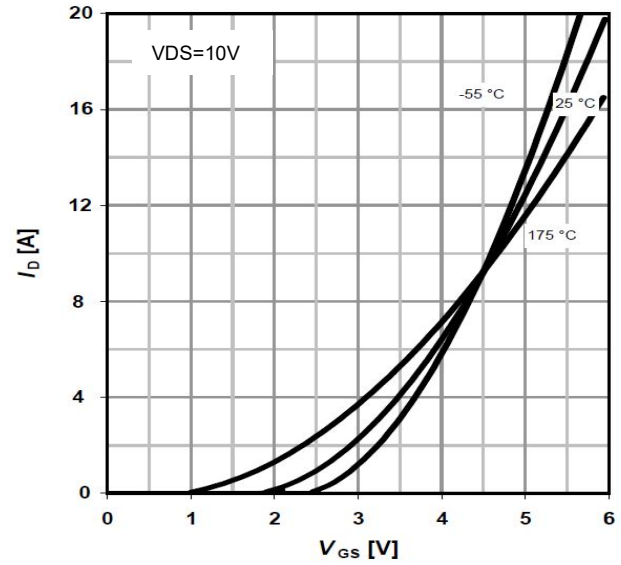
ID -- Tc



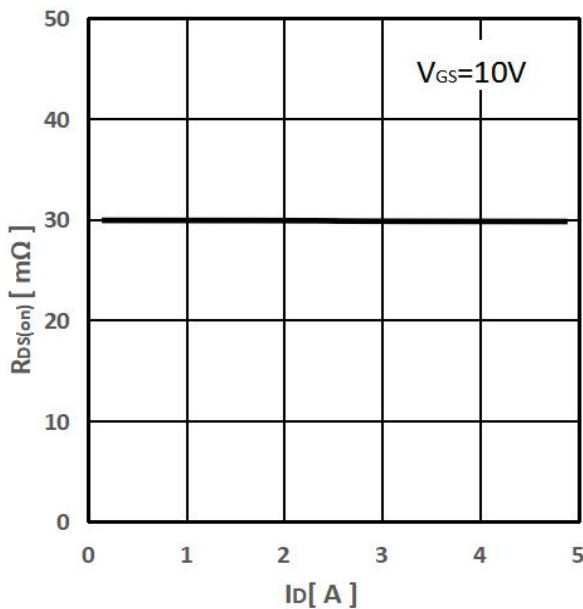
ID -- VDS



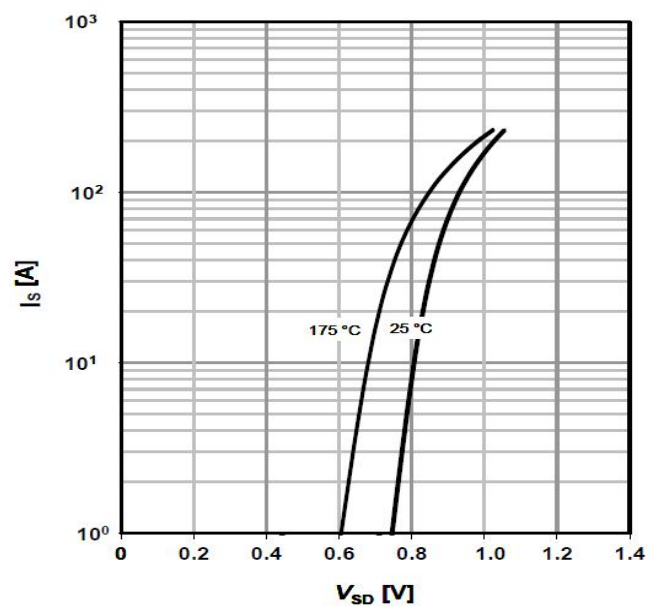
ID -- VGS



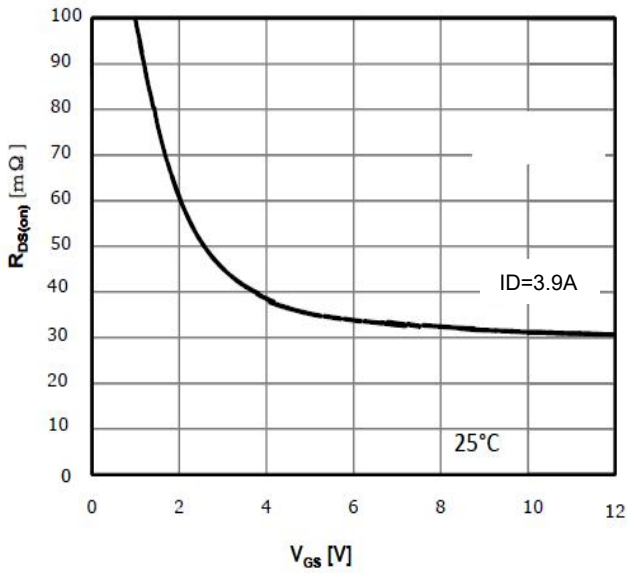
RDS(on) -- ID



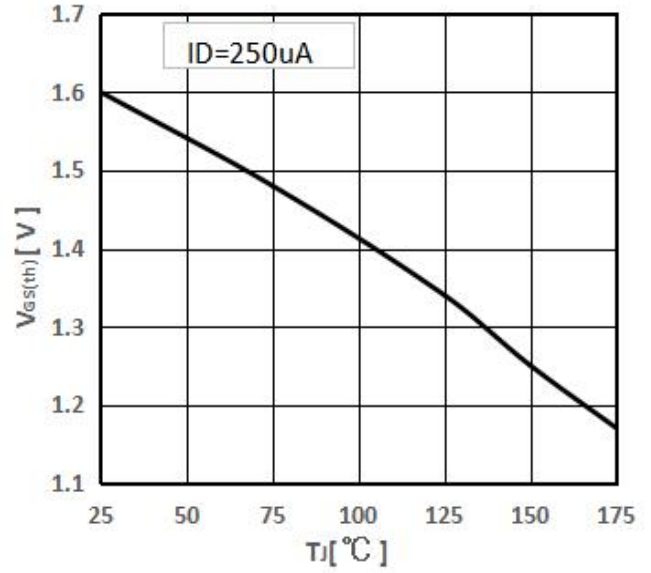
IS -- VSD



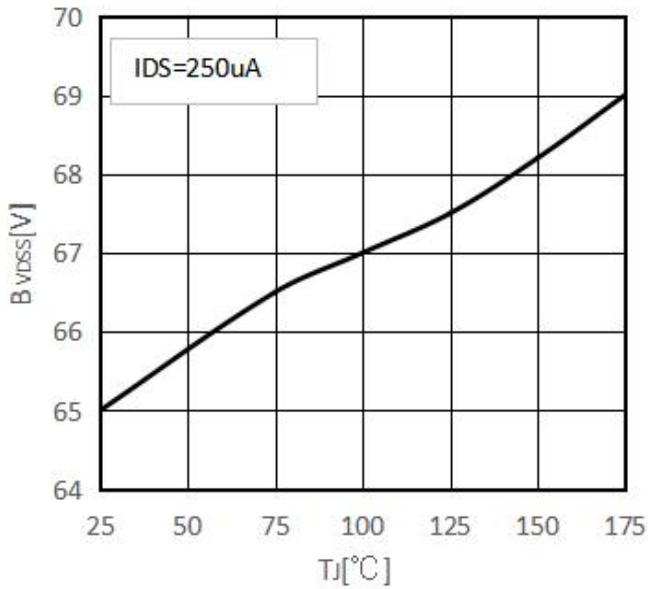
### RDS(on) -- VGS



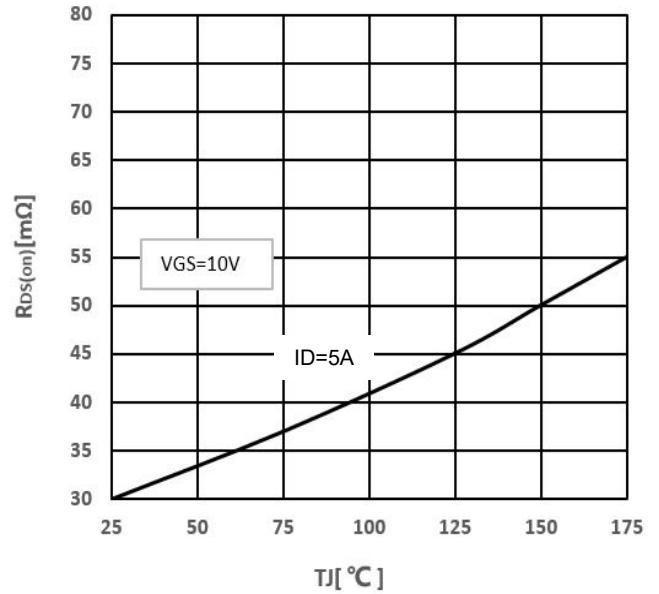
### Threshold Voltage



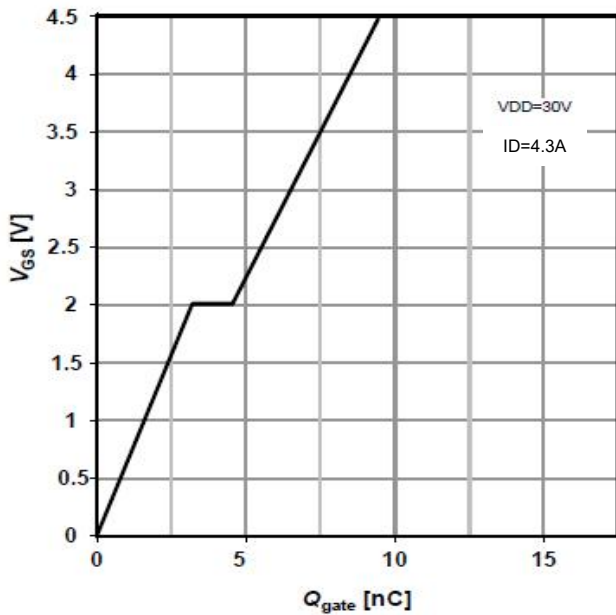
### Drain-source breakdown voltage



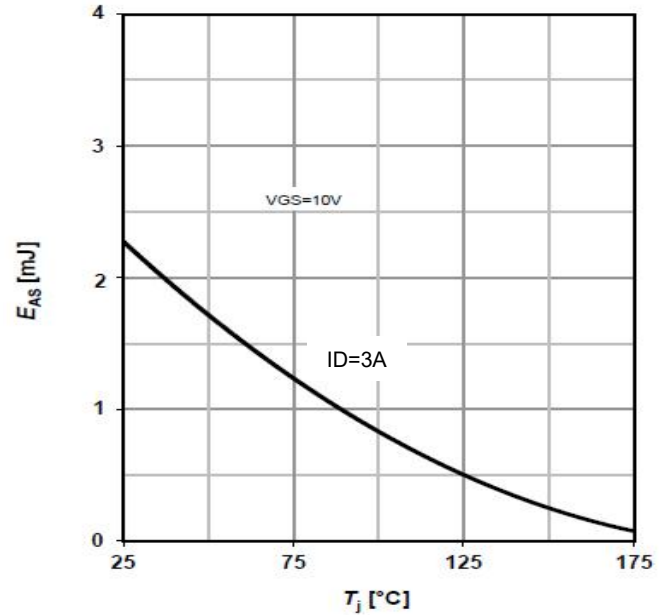
### RDS (on) -- Tj



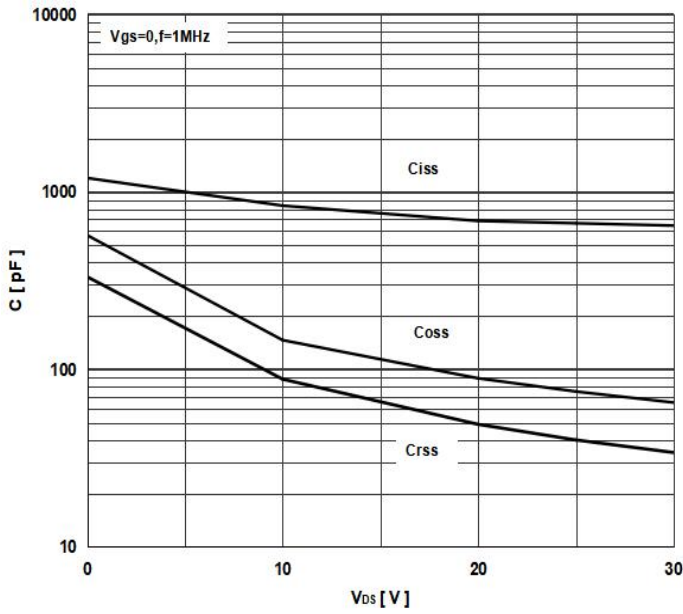
### Typ.gate charge



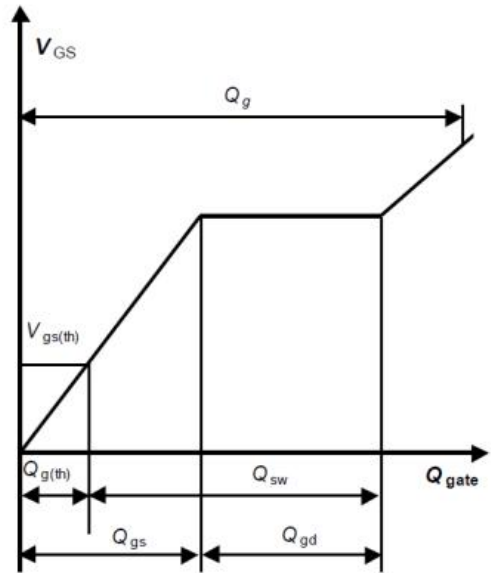
### Avalanche energy



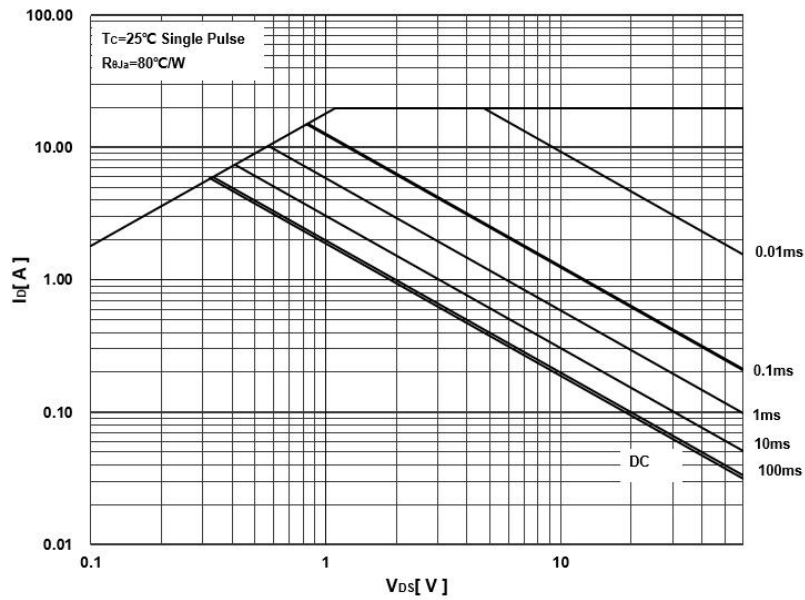
### Typ. capacitance



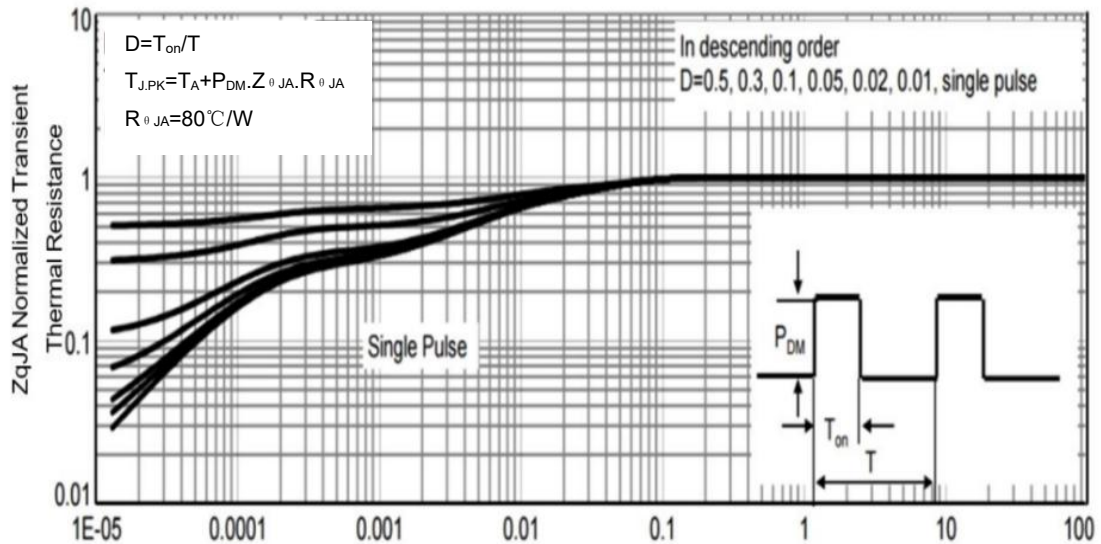
### Gate charge waveforms



### Maximum Forward Biased Safe Operating Area

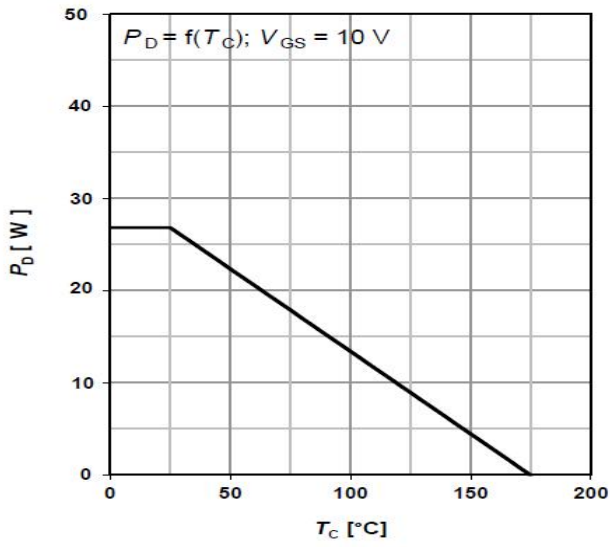


### Normalized Thermal Transient Impedance

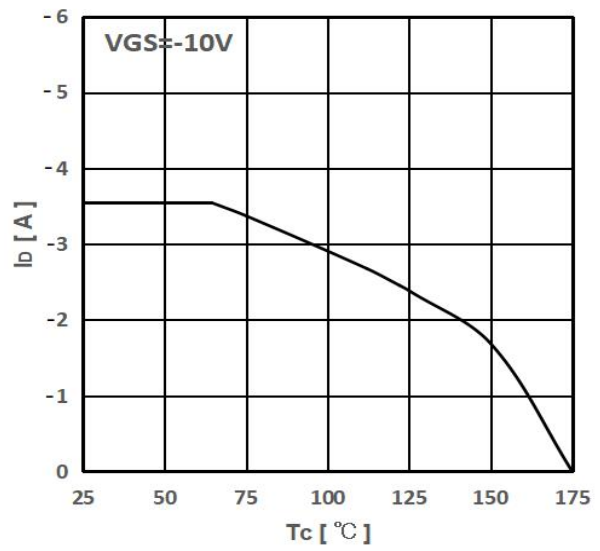


# P-Channel Typical Characteristics

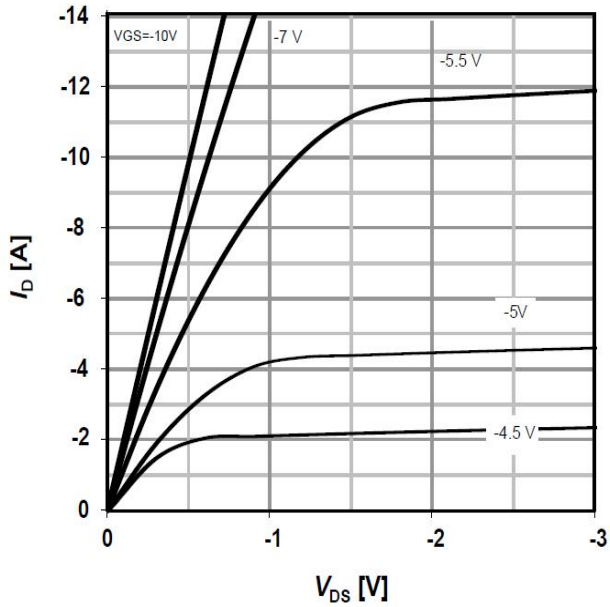
PD -- Tc



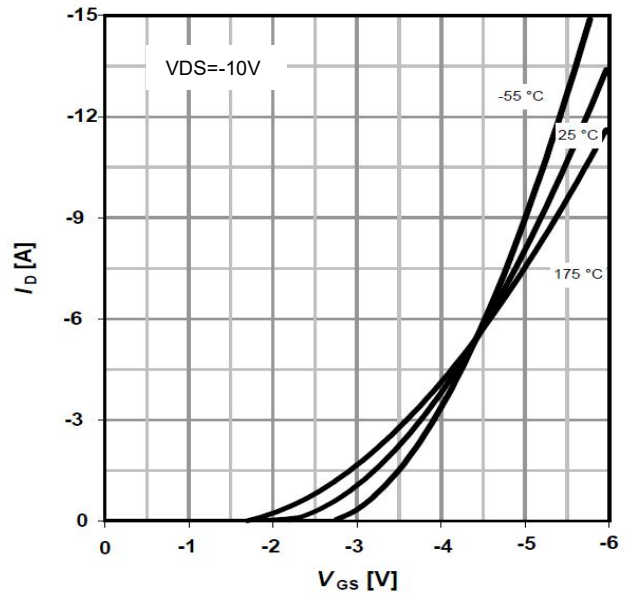
ID -- Tc



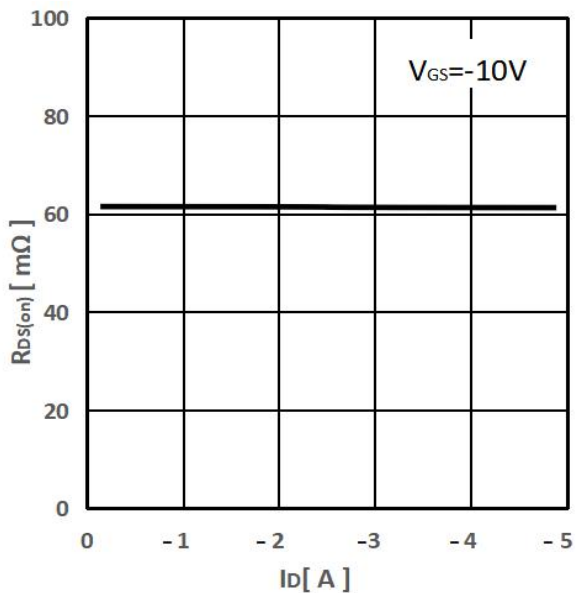
ID -- VDS



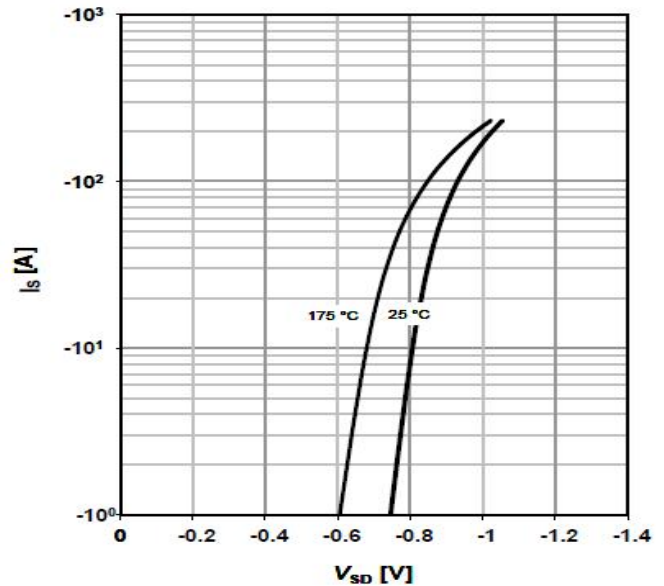
ID -- VGS



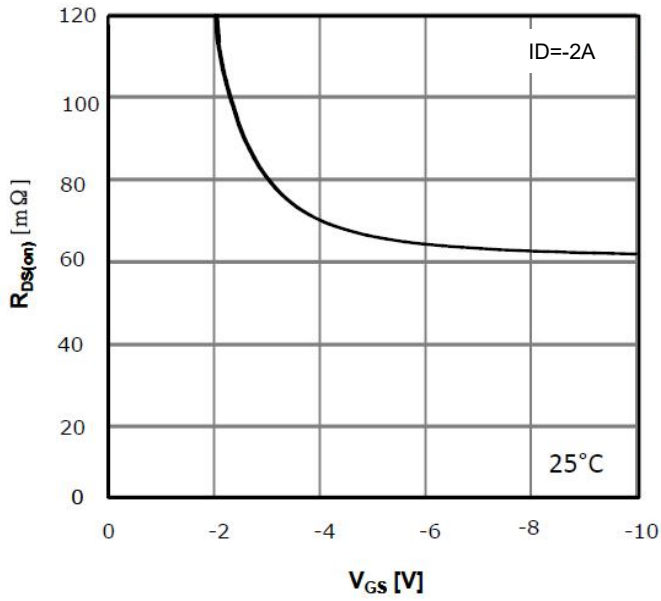
RDS(on) -- ID



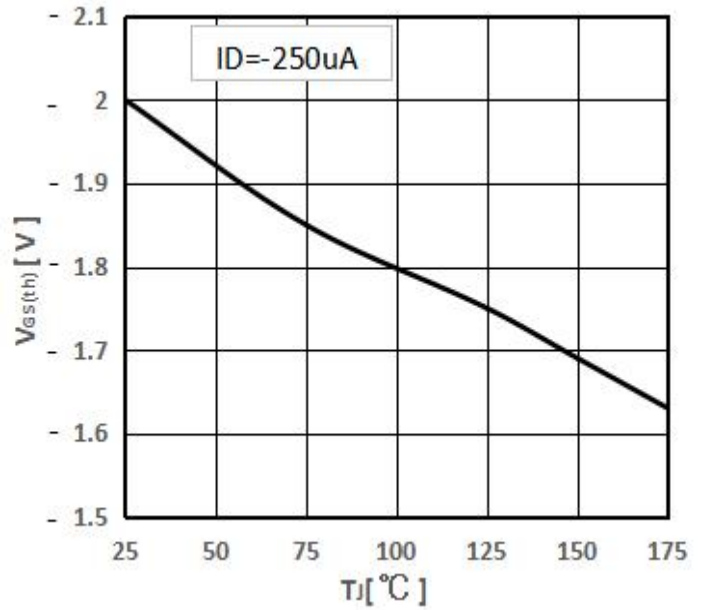
IS -- VSD



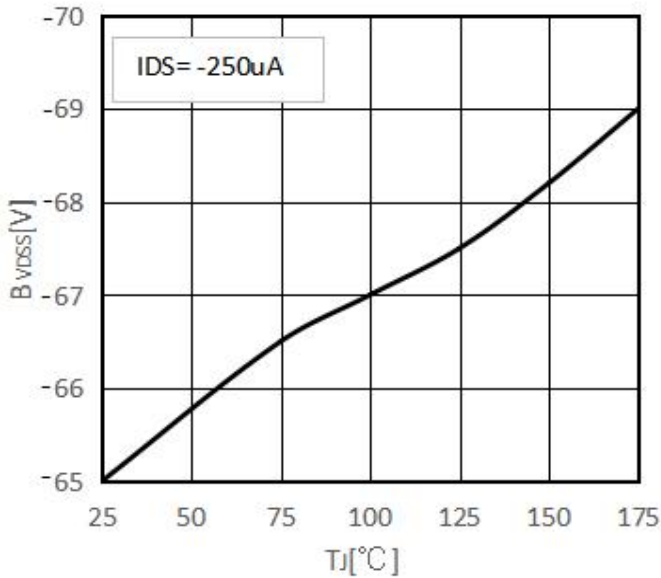
**RDS(on) -- VGS**



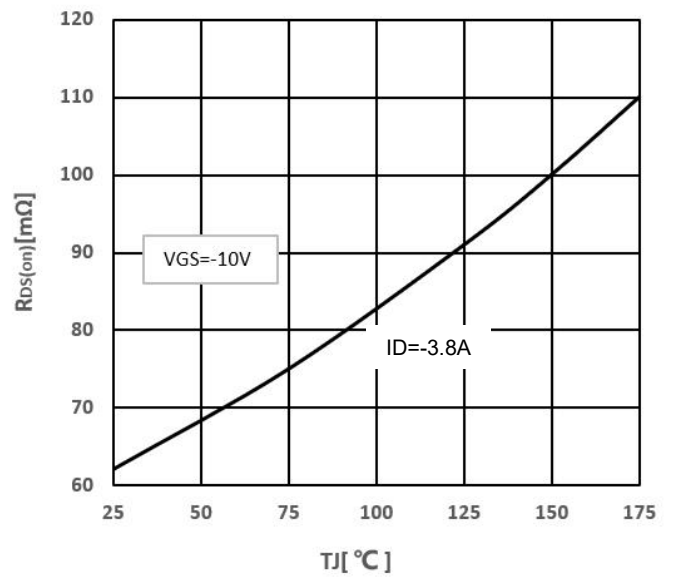
**Threshold Voltage**



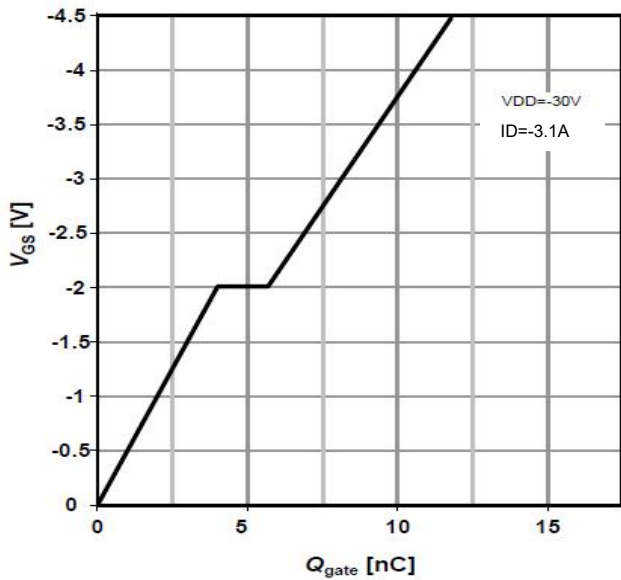
**Drain-source breakdown voltage**



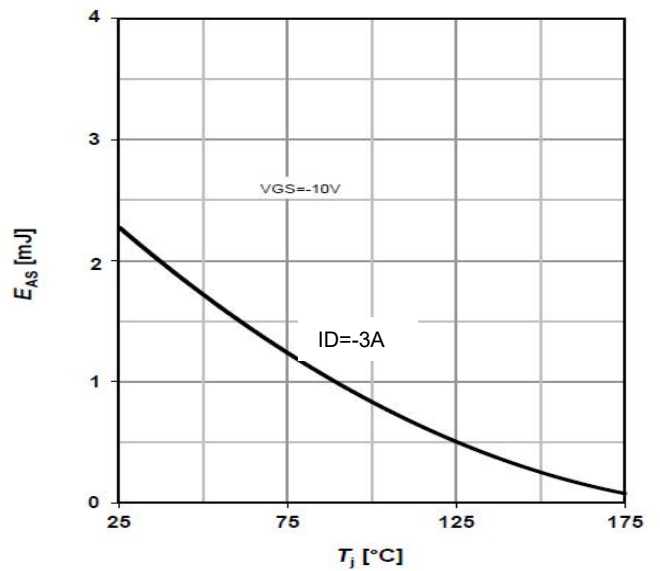
**RDS (on) -- Tj**



**Typ.gate charge**

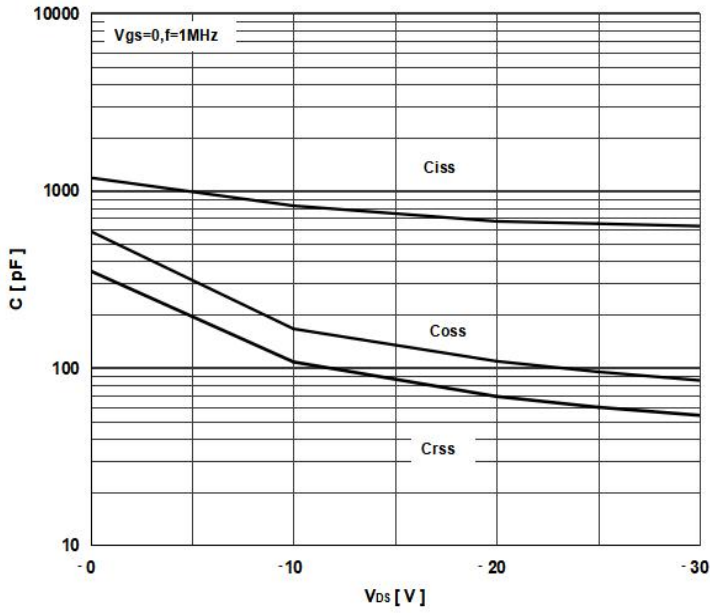


**Avalanche energy**

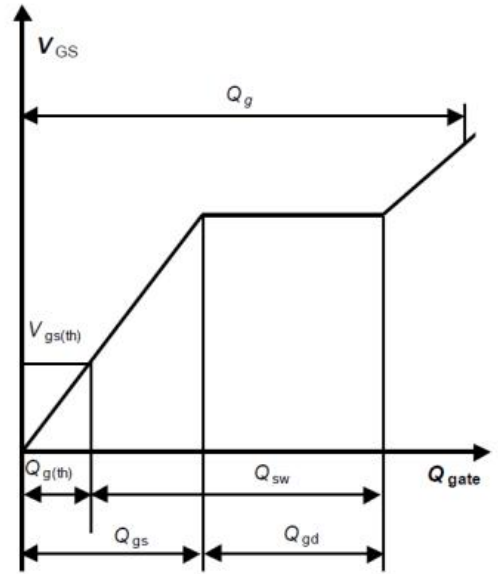




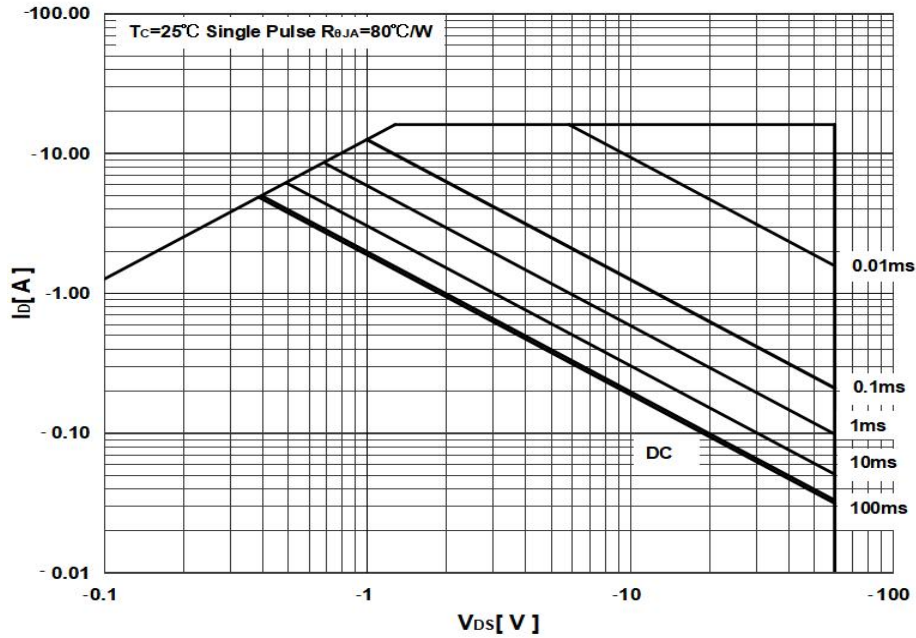
### Typ. capacitance



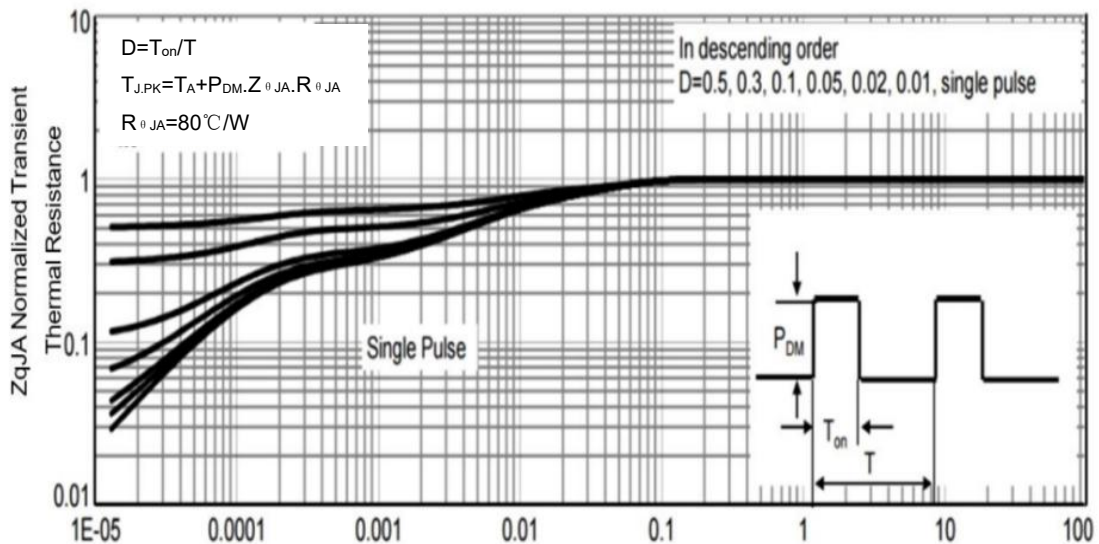
### Gate charge waveforms



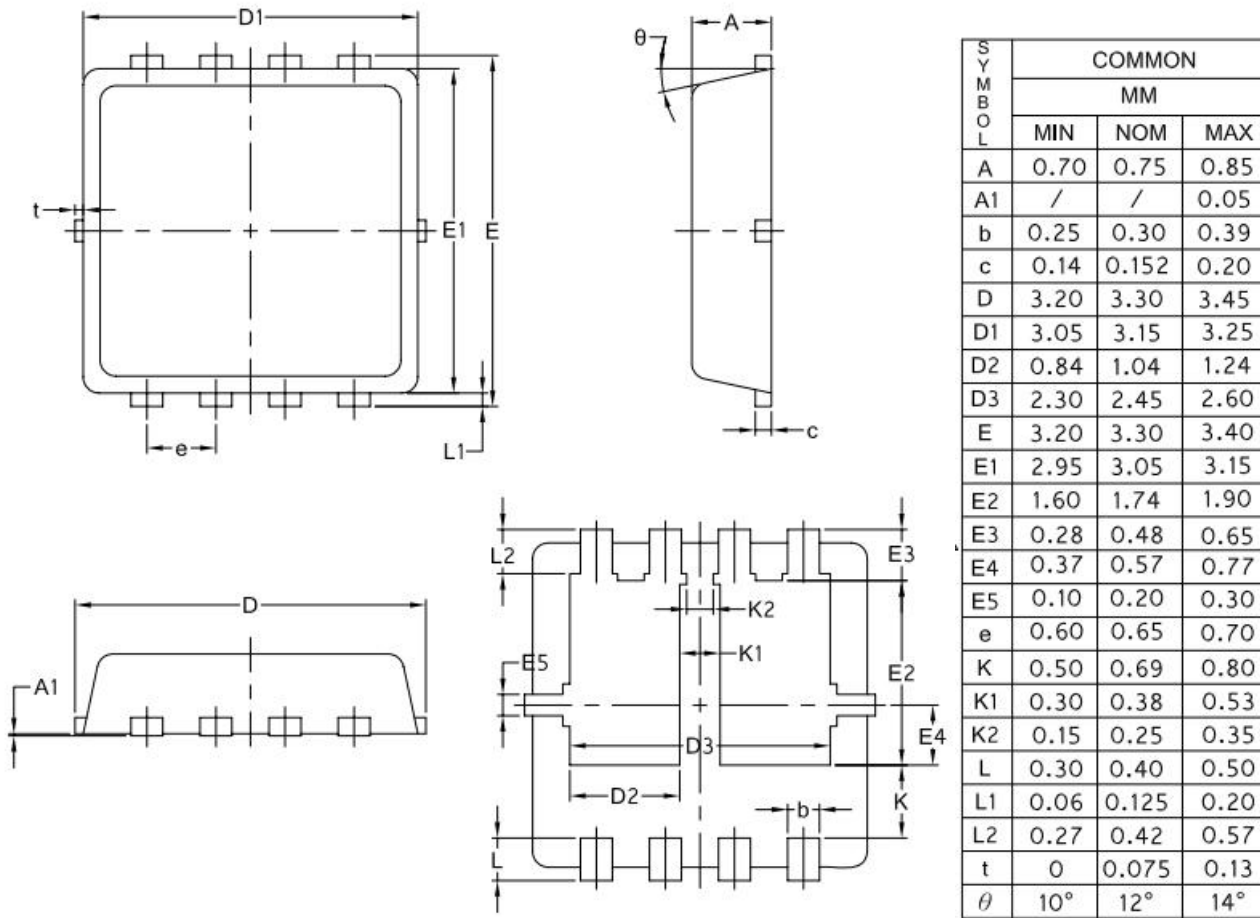
### Maximum Forward Biased Safe Operating Area



### Normalized Thermal Transient Impedance



# PDFN3.3\*3.3-8L Package Outline Dimensions



## NOTICE

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Date of change	Rev #	revise content
2023/11/20	A/0	/
2023/12/14	A/1	修改测试条件